

**REPLY UNDER 37 CFR 1.116
EXPEDITED PROCEDURE
TECHNOLOGY CENTER 2100**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.:	10/065,753	Conf. No.:	9185
Applicant:	Chiu et al.	TC/AU:	2128
Filed:	11/15/02	Examiner:	Phan, Thai Q.
Customer No.:	23550	Docket:	BUR920020064 (IBMB-0012)

Title: INTEGRATED CIRCUIT AND PACKAGE MODELING

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AFTER FINAL AMENDMENT

Sir:

I. INTRODUCTORY COMMENTS:

In response to the Office Action of January 4, 2006, please amend the above-referenced patent application as follows: